Overview

HP Z4 G6i Workstation Desktop PC

Front View

1. Integrated Front Handle
2. Power Button
3. HDD Activity LED
4. Headphone/Microphone combo
5. Front I/O Premium: 2 SuperSpeed USB Type-C™ 20 Gbps signaling rate (USB Power Delivery 3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port has Charging Capability]

   Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port has Charging Capability]
6. SD Card Reader[2]
7. External 5.25" bay

1. Front IO Entry is shown on Photography
2. SD Card Reader available separately

Overview

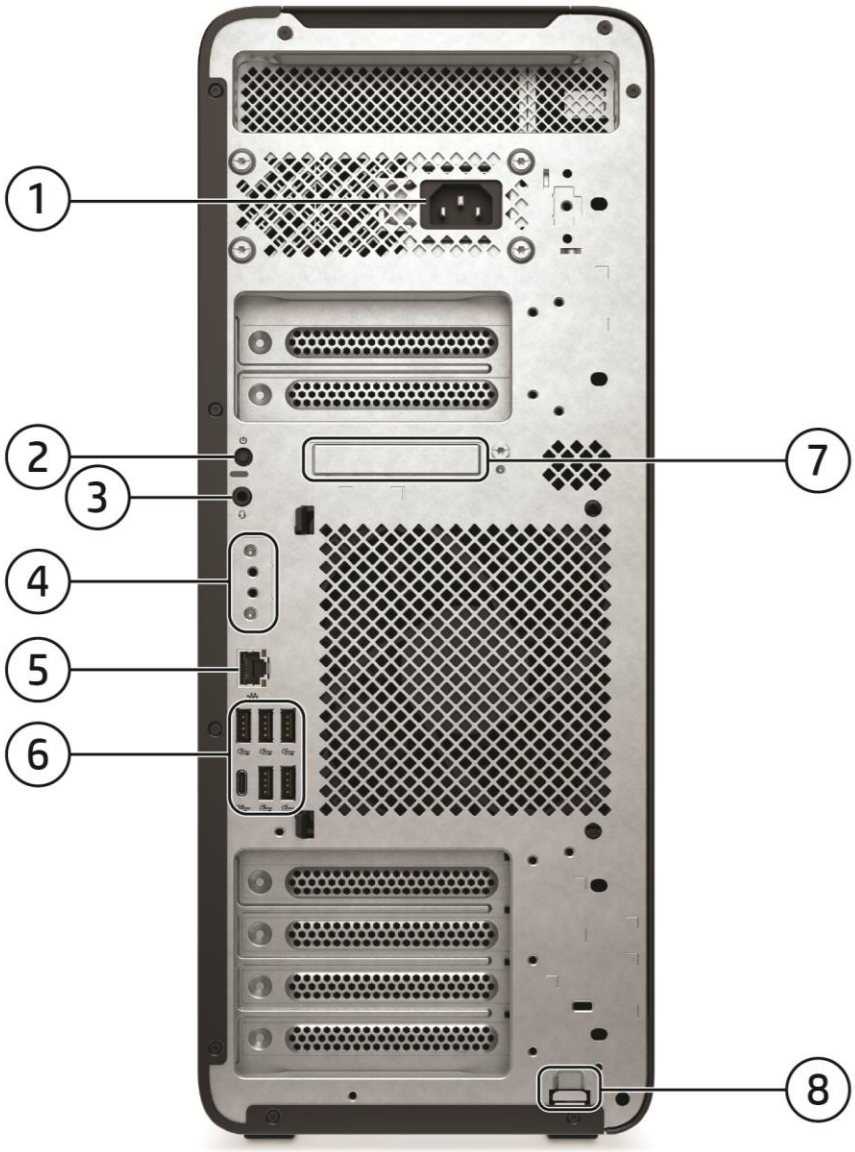
HP Z4 G6i Workstation Desktop PC

Internal View

1. Intel® Xeon® 600 Processors
2. 8 DIMM slots for DDR5 ECC Memory
3. • Slot 1: PCIe x16 Gen5
   • Slot 2: PCIe x4 Gen5
   • Slot 3: PCIe x16 Gen5
   • Slot 4: PCIe x4 Gen4
   • Slot 5: PCIe x16 Gen5
4. 1 External 5.25" bays
5. 1 Internal 3.5" bays
6. 1 Internal NVMe connectors to Front Removable M.2/U.2 Carrier
7. 4 Gen5 M.2 slots on-board
8. 2 SATA Ports
9. 2 Internal USB Ports: 1x USB 2.0 and 1x USB 3.0

Overview

HP Z4 G6i Workstation Desktop PC



Rear View

1. Choice of 2 Power Supplies:
   - 775W, Platinum Rated (92% Efficient)
   - 1350W @110V or 1700W @200V, Platinum Rated (92% Efficient)
2. Rear Power Button
3. Universal Audio Jack with Retasking
4. Flex IO Port.
5. 1x 1GbE AMT RJ-45 integrated LAN port
6. 5x 5Gb SuperSpeed Type-A USB, 1x 10Gb SuperSpeed+ Type-C USB
7. 2x 10GbE or 2x 25GbE LAN ports (optional)
8. Rear Padlock Loop Pullout

Technical Specifications

FORM FACTOR

Tower

OPERATING SYSTEMS

Preinstalled:

- Windows 11 Pro for Workstations[1]
- Ubuntu® 24.04 LTS[2]
- HP Linux®-ready[3]
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)[3]

Supported:

- Windows 11, version 24H2, 25H2[1]
- Red Hat® Enterprise Linux® Workstation 9 & 10[3]
- SUSE Linux® Enterprise Desktop 15 & 16[3]
- Ubuntu® 24.04 LTS[2]

Web-supported only:

- Windows 11 Enterprise[1]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 11 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
2. A certified preloaded version of Ubuntu® 24.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. The update setting is user controllable. ISP fees may apply, and additional requirements may apply over time for upgrades.
3. For detailed OS/hardware support information for Linux, see:
http://www.hp.com/support/linux_hardware_matrix

NOTE: This product does not support Windows 10 A full list of HP products and the Windows 11 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282.

Technical Specifications

PROCESSORS OVERVIEW

Name[1,2,3,4,5]	Cores	Clock Speed (GHz)	Intel® Turbo Boost Technology[2]	Cache (MB)	Max Memory Speed (MT/s)	Hyper-Threading	Featuring Intel® vPro™ Technology[3]	TDP
					1 DIMM Per Channel			
Intel® Xeon® 678X	48	2.4	4.9	192	6400	Yes	Yes	300
Intel® Xeon® 676X	32	2.8	4.9	144	6400	Yes	Yes	275
Intel® Xeon® 674X	28	3.0	4.9	144	6400	Yes	Yes	270
Intel® Xeon® 658X	24	3.0	4.9	144	6400	Yes	Yes	250
Intel® Xeon® 656	20	2.9	4.8	72	6400	Yes	Yes	210
Intel® Xeon® 654	18	3.1	4.8	72	6400	Yes	Yes	200
Intel® Xeon® 638	16	3.2	4.8	72	6400	Yes	Yes	180
Intel® Xeon® 636	12	3.5	4.8	48	6400	Yes	Yes	170
Intel® Xeon® 634	12	2.7	4.7	48	6400	Yes	Yes	150

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
3. Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro.
4. Processor speed denotes maximum performance mode.
5. Features and software that require a NPU may require software purchase, subscription or enablement by a software or platform provider, and third party software may have specific configuration or compatibility requirements. Performance varies by use, configuration, and other factors.

Color	Black
Convertibility	No
Expansion Slots (see system board section for more details)	• Slot 1: PCIe x16 Gen5 • Slot 2: PCIe x4 Gen5 • Slot 3: PCIe x16 Gen5 • Slot 4: PCIe x4 Gen4 • Slot 5: PCIe x16 Gen5
Expansion Bays (see storage section for more details)	1 internal 3.5" bay 1 external 5.25" bay
Front I/O	Front I/O Premium: 2 SuperSpeed USB Type-C™ 20 Gbps signaling rate (USB Power Delivery 3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port has Charging Capability] Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port has Charging Capability]
Internal I/O	2 internal USB ports, 2 SATA ports, and 1 NVMe connector
Rear I/O	Universal Audio Jack with Retasking, 5x 5Gb SuperSpeed Type-A USB, 1x 10Gb SuperSpeed+ Type-C USB

Technical Specifications

On-board RAID Support	RAID 0 Striped Array RAID 1 Mirrored Array RAID 10 Striped/Mirrored RAID 5 Parity Array (See System Board Section for further details and configuration options)
Chassis Dimensions (H x W x D)	With Standard Side Panel: H: 17.2" [438.2mm] W: 6.9" [175.0mm] D: 18.5" [469.9mm] With Max Side Panel: H: 17.2" [438.2mm] W: 8.3" [209.8mm] D: 18.5" [469.9mm]
Packaged Dimensions	EPE & Hybrid Packaging: H: 23.35" [593mm] W: 12.32" [313mm] D: 24.02" [610mm] Max Side Panel EPE Packaging: H: 24.8" [629mm] W: 13.8" [351mm] D: 24.1" [612mm]
Rack Dimensions	4U (with Standard Side Panel) 5U (with Max Side Panel)
Power Supply	Choice of 2 Power Supplies: • 775W, Platinum Rated (92% Efficient) • 1350W @110V or 1700W @200V or higher, Platinum Rated (92% Efficient)
Workstation ISV Certifications	See the latest list of certifications at https://www.hp.com/us-en/workstations/isv-certifications/mcad-isv-certification.html?jumpid=va_6fsqyhva81
Chipset	Intel® W890 Chipset
Memory	8 DIMM slots, supporting up to 64GB RDIMMs, DDR5 6400 MT/s speed at 1DPC (2DPC is 5200 MT/s)

System Technical Specifications

PROCESSORS

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® Xeon® 678X	Y	N		
Intel® Xeon® 676X	Y	N		
Intel® Xeon® 674X	Y	N		
Intel® Xeon® 658X	Y	N		
Intel® Xeon® 656	Y	N		
Intel® Xeon® 654	Y	N		
Intel® Xeon® 638	Y	N		
Intel® Xeon® 636	Y	N		
Intel® Xeon® 634	Y	N		

SATA HARD DRIVES

	Factory Configured	Option Kit	Option Kit Part Number
4TB 7200RPM SATA 3.5in Enterprise HDD	Y	Y	K4T76AA
8TB 7200RPM SATA 3.5in Enterprise HDD	Y	Y	2Z273AA
12TB 7200 RPM SATA-6G 3.5in Enterprise HDD	Y	Y	5S461AA
HP Z4/Z6 A HDD Cable Kit	N	Y	74Y88AA
HP Optical Bay HDD Mounting Bracket-BLK	N	Y	NQ099AA

PCIe SOLID STATE DRIVES

	Factory Configured	Option Kit	Option Kit Part Number
HP Z Turbo 512GB PCIe-4x4 2280 TLC M.2 SSD	Y	N	
HP Z Turbo 512GB PCIe-4x4 2280 SED OPAL2 TLC M.2 SSD	Y	N	
512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	Y	N	
Citadel 512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	Y	N	
HP Z Turbo 1TB PCIe-4x4 2280 TLC M.2 SSD	Y	Y	38T77AA
HP Z Turbo 1TB PCIe-4x4 2280 SED OPAL2 TLC M. SSD	Y	Y	38T76AA
1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	Y	N	
Citadel 1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M SSD	Y	N	
HP Z Turbo 1TB PCIe-5x4 2280 M.2 SSD	Y	Y	B54YVAA
HP Z Turbo 1TB PCIe-5x4 2280 SED OPAL2 M.2 SSD	Y	Y	B54YXAA
HP Z Turbo 2TB PCIe-4x4 2280 TLC M.2 SSD	Y	Y	38T75AA
HP Z Turbo 2TB PCIe-4x4 2280 SED OPAL2 TLC M.2 SSD	Y	Y	38T79AA
HP Z Turbo 2TB PCIe-5x4 2280 M.2 SSD	Y	Y	B54YWAA

System Technical Specifications

	Factory Configured	Option Kit	Option Kit Part Number
HP Z Turbo 2TB PCIe-5x4 2280 SED OPAL2 M.2 SSD	Y	Y	B54YYAA
HP Z Turbo 4TB PCIe-4x4 2280 M.2 SSD	Y	Y	5S496AA
HP Z Turbo 4TB PCIe-4x4 2280 SED OPAL2 M.2 SSD	Y	Y	5S497AA
HP Z Turbo 4TB PCIe-5x4 2280 M.2 SSD	Y	Y	B54XBAA
HP Z Turbo 8TB PCIe-4x4 2280 NVMe M.2 SSD	Y	N	
HP Z Turbo 1TB 2280 PCIe-5x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X7AA
HP Z Turbo 1TB 2280 PCIe-5x4 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X6AA
HP Z Turbo 2TB 2280 PCIe-5x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X9AA
HP Z Turbo 2TB 2280 PCIe-5x4 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X8AA
HP Z Turbo 2TB PCIe-4x4 TLC China Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WYAA
HP Z Turbo 1TB 2280 PCIe-4x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WVAA
HP Z Turbo 1TB PCIe-4x4 TLC China Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WSAA
HP Z Turbo 1TB PCIe-4x4 TLC Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WTAA
HP Z Turbo 2TB 2280 PCIe-4x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X0AA
HP Z Turbo 2TB PCIe-4x4 TLC Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WZAA
HP Z Turbo 4TB 2280 PCIe-4x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X5AA
HP Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54X4AA
HP Z Turbo 4TB 2280 PCIe-5x4 M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54XCAA
HP Z Turbo 4TB 2280 PCIe-5x4 Self Encrypted OPAL2 M.2 SSD Module - NEW AMO	N	Y	B54XDAA
HP Z Turbo 4TB 2280 PCIe-5x4 Self Encrypted OPAL2 M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54XFAA
HP Z Turbo 512GB 2280 PCIe-4x4 Self Encrypted OPAL2 TLC M.2 Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WRAA
HP Z Turbo 512GB PCIe-4x4 TLC Z4/Z8 Fury Kit SSD - NEW AMO	N	Y	B54WQAA

System Technical Specifications

HP Z Turbo Drive Quad Pro	Factory Configured	Option Kit	Option Kit Part Number
HP Z Turbo Drive Quad Pro 1TB 2280 PCIe-5x4 NVMe TLC SSD	Y	N	
HP Z Turbo Drive Quad Pro 2TB 2280 PCIe-5x4 NVMe TLC SSD	Y	N	
HP Z Turbo Drive Quad Pro 4TB 2280 PCIe-5x4 NVMe TLC SSD	Y	N	
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			
Intel VROC NVMe SSD Premium Controller Module	Y	Y	3FJ81AA
Intel VROC NVMe SSD Standard Controller Module	Y	Y	3FJ80AA

NOTE: Intel® VROC NVMe SSD Premium and Standard Controller Modules will be available Summer 2026.
NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.
NOTE: PCIe M.2 SSD Kit SKUs include a heatsink. PCIe M.2 SSD Module SKUs do not include a heatsink and are compatible with the HP Front Removable Carrier and the HP Z Turbo Quad Pro PCIe-5x16 NVMe Carrier.

GRAPHICS

Graphics Cable Adapters	Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	Support Notes
HP DP to HDMI 2.0	Y	Y	2JA63AA		
HP miniDP-to-DP Adapter	Y	Y	2MY05AA		
HP miniDP-to-DP Adapter (2-pack)	Y	N			
HP miniDP-to-DP Adapter (4-pack)	Y	N			
HP miniDP-to-DP Adapter (8-pack)	Y	N			
HP Mini DisplayPort to DisplayPort Adapter Cable Bulk 12)	N	Y	2KW87A6		
HP DisplayPort to VGA Adapter (Marlin)	N	Y	F7W97AA		
HP Graphics Cable Kit	N	Y	B5CJ4AA		

Entry 3D	Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	Support Notes
NVIDIA RTX A400 4 GB 4mDP Graphics	Y	Y	AV8J3AA	2	
NVIDIA RTX A1000 8 GB 4mDP Graphics	Y	Y	AV8J4AA	2	

Mid-range 3D	Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	Support Notes
NVIDIA RTX PRO 2000 Blackwell 16 GB 4mDP Graphics	Y	Y	B5CH7AA	2	
NVIDIA RTX PRO 4000 Blackwell 24 GB 4DP Graphics	Y	Y	B11F3AA		

System Technical Specifications

High-End 3D	Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	Support Notes
NVIDIA RTX PRO 4000 Blackwell 24 GB 4DP Graphics	Y	Y	B11F3AA	2	
NVIDIA RTX PRO 4500 Blackwell 32 GB 4DP Graphics	Y	Y	B11F2AA	2	
NVIDIA RTX PRO 5000 Blackwell 48 GB 4DP Graphics	Y	Y	B11F1AA	2	
Ultra High-End 3D					
NVIDIA RTX PRO 6000 Blackwell Max-Q 300W 96 GB 4DP Graphics	Y	Y	B11E9AA	2	
NVIDIA RTX PRO 6000 Blackwell 96 GB 4DP Graphics	Y	Y	B11F0AA	1	
NVIDIA A800 40 GB Graphics	Y	Y	8D6C0AA	1	
Other options					
NVIDIA Quadro Sync II Graphics	N	Y	1WT20AA		
NVIDIA RTX PRO Sync Card	N	Y	C08YVAA		
NVIDIA 3D Stereo Bracket - NEW AMO	N	Y	K0A25AA		

MEMORY

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
16GB (1x16GB) DDR5 6400 DIMM ECC REG Memory	Y	Y	B55A9AA	
32GB (1x32GB) DDR5 6400 DIMM ECC REG Memory	N	Y	B55B0AA	
64GB (1x64GB) DDR5 6400 DIMM ECC REG Memory	N	Y	B55B1AA	

Note 1: For details on the supported memory configurations on the HP Z8 Fury G6i Workstation, please refer to the System Technical Specifications - System Board section of this document.
Note 2: The CPUs determine the speed at which the memory is clocked. If a 6400 MHz capable CPU is used in the system, the maximum speed the memory will run at is 6400 MHz regardless of the specified speed of the memory. If the memory speed is rated lower than the CPU capability (ie – 5600 MHz) the whole system will run at this slower speed.

OPTICAL AND REMOVAL STORAGE

	Factory Configured	Option Kit	Option Kit Part Number
HP PCIe - Gen5 Front Removable M.2/U.2 2-in-1 Frame/Carrier	Y	Y	B5CK8AA
512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	
Citadel 512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	
1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	

System Technical Specifications

	Factory Configured	Option Kit	Option Kit Part Number
Citadel 1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	
2TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	
Citadel 2TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 Front Load Removable SSD	Y	N	
HP Z Turbo 1TB PCIe-4x4 2280 TLC U2M2 Front Load Removable SSD	Y	N	
HP Z Turbo 2TB PCIe-4x4 2280 TLC U2M2 Front Load Removable SSD	Y	N	
HP Z Turbo 4TB PCIe-4x4 2280 TLC U2M2 Front Load Removable SSD	Y	N	
HP Z Turbo 8TB PCIe-4x4 2280 NVMe M.2 Front Load Removable SSD	Y	N	
HP Z Turbo 1TB PCIe-5x4 2280 TLC M.2 Front Load Removable SSD	Y	N	
HP Z Turbo 2TB PCIe-5x4 2280 TLC M.2 Front Load Removable SSD	Y	N	
HP Z Turbo 4TB PCIe-5x4 2280 TLC M.2 Front Load Removable SSD	Y	N	
9.5mm DVD-ROM 1st ODD	Y	Y	K3R63AA
9.5mm DVD-Writer 1st ODD	Y	Y	K3R64AA
HP PCIe - Gen5 Front Removable M.2/U.2 Spare Carrier - (AMO)		Y	B54ZMAA
HP Z Turbo Drive Quad Pro PCIe-5x16 NVMe Carrier - (AMO)		Y	B54Z1AA

Note: Option Kits for Front Accessible are listed in SSD AMO as Modules. Front Removable supports all of them.

NETWORKING AND COMMUNICATIONS

	Factory Configured	Option Kit	Option Kit Part Number
AT-2914SX/LC PCIe Fiber Adapter	Y	Y	1C7Q2AA
Allied Telesis AT-2911Ta/2-901 Dual Port 1GbE NIC[1]	Y	Y	6E3Y9AA
Broadcom 5720 1GbE RJ45 PCIe Ethernet Network Adapter	Y	Y	9Z7P1AA
Intel I226-T1 2.5GbE Ethernet Network Adapter[1]	Y	Y	9P1U8AA
Intel X550-T2 10GbE Dual Port NIC	Y	Y	1QL46AA
HP Dual Port 10GBase-T NIC Module G2	Y	Y	360K6AA
HP 10/25GbE SFP28 Fiber Network Module	Y	Y	B5CL0AA
NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC[1]	Y	Y	436M8AA
Intel E810-CQDA2 1x100GbE/2x50GbE QSFP28 PCIe Network Adapter[1]	Y	Y	D0SX1AA
HP MT7925 Wi-Fi 7 +Bluetooth 5.4 WLAN with External Antenna	Y	Y	B5CL1AA
HP FlexIO MT7925 Wi-Fi 7 + Bluetooth 5.4 WLAN with Internal	Y	N	

System Technical Specifications

Antenna			
HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Y	Y	860T8AA
HP 25GbE SFP28 LC Fiber Optic Transceiver	Y	Y	860T9AA
Intel i350-T4 Quad Port 1Gb NIC	N	Y	W8X25AA

1. Available Summer 2026.

REMOTE SYSTEM CONTROLLER

	Factory Configured	Option Kit	Option Kit Part Number
HP Integrated Remote System Controller	Y	Y	7K6D9AA
HP Remote System Controller	Y	Y	7K6D7AA
HP Remote System Controller Main Board Adapter	Y	Y	7K6D8AA

RACKING AND PHYSICAL SECURITY

	Factory Configured	Option Kit	Option Kit Part Number
HP Z4/Z8 Fury G6i Rail Rack Kit	N	Y	B5CJ0AA
HP Smart Cover Enable Safety Interlock and Cover Removal Sensor	Y	N	
HP Keyed Cable Lock		Y	T1A62AA
HP Master Keyed Standard Cable Lock		Y	T1A63AA

INPUT DEVICES

	Factory Configured	Option Kit	Option Kit Part Number
HP Black 125 Wired Mouse	Y	Y	265A9AT
HP Wired 128 LSR Mouse	Y	Y	265D9AA
HP Wired 320M Mouse	Y	Y	9VA80AA
HP 125 v2 Black Wired Keyboard	Y	Y	AY2Y7AA
HP 320K v2 Keyboard	Y	Y	9SR37UT
HP 725 Multi-Device Rechargeable Wireless Keyboard and Mouse Combo	Y	Y	9T5B2AA
HP Bus Slim v2 Smart Card Wired Keyboard	Y	Y	A71J9AA
HP 125 G2 Wired USB Keyboard (Bulk 12)	N	Y	AY2Y7A6
HP 320K G2 Wired USB Keyboard (Bulk 12)	N	Y	9SR37A9
HP 435 Programmable BT Keypad	N	Y	7N7C3AA
HP 485 Comfort Wired Keyboard	N	Y	8T6M2AA
HP 685 Comfort Dual-Mode Keyboard	N	Y	8T6L9UT

System Technical Specifications

	Factory Configured	Option Kit	Option Kit Part Number
HP 655 Wireless Keyboard and Mouse Combo G2 (Blk 9)	N	Y	4R009A9
HP 655 Wireless Keyboard and Mouse Combo G2	N	Y	4R009UT
HP 685 Comfort Dual-Mode Keyboard and Mouse Combo	N	Y	8T6L7UT
HP Wired Desktop 320MK Mouse and Keyboard G2	N	Y	9SR36UT
HP 920 Ergonomic Vertical Bluetooth 5.0 + Wireless 2.4GHz Wireless Mouse	N	Y	6H1A4AA
HP Creator USB-A+Bluetooth® 935 Wireless Mouse Black	N	Y	1D0K8AA

FLEX MODULE (Rear IO)

	Factory Configured	Option Kit	Option Kit Part Number
HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA
HP Flex 1GbE Fiber LC Single Port	Y	Y	20J15AA
HP Serial Port v3 Flex IO	Y	Y	5B895AA
HP 10GBase-T Flex IO v2	Y	Y	CF8G5AA
HP 2.5GbE LAN Flex Port	Y	Y	169K0AA
Dual Type-A 3.2 Gen 1 Flex IO v2	Y	Y	141J8AA
Dual Type-C 3.2 Gen2 15W Out Flex IO	Y	Y	B6BT5AA

OTHER HARDWARE

	Factory Configured	Option Kit	Option Kit Part Number
HP Serial Port Internal Adapter	Y	Y	B5CH9AA
HP Z4 G6i Max Side Panel	Y	Y	BY2F7AA
HP Z4 G6i Fan and Front Card Guide Kit	Y	Y	BZ2R2AA
HP Dual TBT5 PCIe x4 Low Profile Card	Y	Y	B15HRAA
HP USB Type-A 2.0 Internal Prt Adpt Kt	Y	Y	79C24AA
HP SD Card Reader	Y	N	
Type-A SuperSpeed USB 5Gbps Front IO v2 Entry Module	Y	N	
Type-C SuperSpeed USB 20Gbps Front IO v2 Premium Module	Y	Y	B5CJ1AA
C13-C14 2.0m 10A 200-240V Countries Straight Rack Power Cord	Y	Y	#N/A
C13-C14 2.0m 15A 100-127V Countries Straight Rack Power Cord	Y	Y	8R881AA
C13 1.83m Power Cord Kit - NEW AMO	N	Y	6Z1T9AA
HP Z4 G6i Fan and Front Card Guide Extra Long Graphics - NEW AMO	N	Y	CM3R7AA
HP Z4 G6i Memory Cooling Solution - NEW AMO	N	Y	BZ2R1AA
Side Panel Barrel Keylock	Y	N	

System Technical Specifications

SOFTWARE

	Factory Configured	Option Kit
HP PC Hardware Diagnostics UEFI (Windows OS only)[1]	Y	N
HP PC Hardware Diagnostics Windows[1]	Y	N
HP Wolf Security[1,2]	Y	N
HP Notifications[1]	Y	N
HP Desktop Support Utility[1]	Y	N
HP Documentation[1]	Y	N
myHP[1]	Y	N
Kingsoft WPS Office[1,3]	Y	N
Z by HP Data Science Stack Manager[4]	Y	N
HP Image Assistant[1]	N	N
HP Support Assistant[1]	N	N
HP IQ[5]		

1.Windows OS only.
2. Not available in Russia.
3. Only available in China.
4. Optional software.
5. HP IQ delivery app is preloaded on select HP PCs; it will be automatically updated to the future featured HP IQ application if you have auto updates enabled in Windows or will be available for download from the Microsoft Store. The future featured HP IQ app uses artificial intelligence. Features vary by configuration. For complete details see https://support.hp.com/us-en/document/ish_13696672-13696717-16.

OPERATING SYSTEMS

Windows 11 Pro for Workstations[1]

Ubuntu 24.04 LTS[2]

Linux®-ready[3]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 11 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
2. A certified preloaded version of Ubuntu® 24.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. The update setting is user controllable. ISP fees may apply, and additional requirements may apply over time for upgrades.
3. For detailed OS/hardware support information for Linux, see:
http://www.hp.com/support/linux_hardware_matrix

System Technical Specifications

BIOS

Key features of the HP BIOS include:

• Deployment and manageability – HP BIOS provides several technologies that help integrate the Z4 G6i into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
• Network firmware updates –Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
• Stability – HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
• Class 3 UEFI specification version 2.9
• Absolute Persistence agent – For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
• Thermal and power management – The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
• Acoustic performance – Industry leading acoustic emissions across the range of operating conditions.
• Serviceability – HP BIOS provides diagnostic and detailed service information.
• Upgrades and recovery – HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
• HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery.

Additional HP BIOS Features:
• Power-On password – Helps prevent an unauthorized user from powering on the system.
• Administrator password – Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
• S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
-Power to expansion connectors / slots
-Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
-USB charging ports

• Sure Start Gen 8
-BIOS Integrity checking – Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on
- Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability

- Protecting beyond BIOS – Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled – System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS
Absolute Persistence Module[1]
BIOS Update via Network
Ultimate Performance Mode
HP BIOSphere Gen4[2]
HP DriveLock & Automatic DriveLock
Power On Authentication
Secure Erase[3]

Application Software
Data Science Stack
HP Z Remote Graphics Software (RGS)
HP Anyware Documentation and Trial
HP PC Hardware Diagnostics UEFI
HP PC Hardware Diagnostics Windows
HP Privacy Settings
myHP

Manageability Software and Features
HP BIOS Config Utility (BCU)
HP Client Catalog
HP Driver Packs[4]
HP Image Assistant
HP Manageability Integration Kit Gen6[5]
HP System Software Manager (SSM)

Security Software and Management
Firmware Health and Insights
HP Client Security Manager Gen7[6]
HP Platform Certificate
HP Pro Wolf Security (Including Credential Manager)
HP Security Update Service (SUS)
HP Smart Cover Enable Safety Interlock and Cover Removal Sensor
HP Sure Recover[7]
HP Sure Run[8]
HP Sure Start Gen8[9]
HP Wolf Security (Including HP Sure Click[10] & HP Sure Sense[11])[12]

Physical Presence Rollback
Power-on password (viaBIOS)
RAID configurations[13]
SATA port disablement (viaBIOS)
Serial, USB enable/disable (viaBIOS)
Setup password (viaBIOS)
TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified)[14]

Setup and Support
HP Desktop Support Utility
HP Notifications
HP Support Assistant[15]

1. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software. Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
2. HP BIOSphere features may vary depending on the platform and configurations.
3. HP Secure Erase - –or the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 “C“ear” ”anitation method. HP Secure Erase does not support platforms with Intel® Optane.
4. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
5. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
6. HP Client Security Manager requires Windows and is available on the select HP PCs.
7. HP Sure Recover is available on select HP PCs and requires Windows 11 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.
8. HP Sure Run is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
9. HP Sure Start is available on select HP PCs and workstations. See product specifications for availability.
10. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
11. HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
12. HP Wolf Pro Security Edition is available preloaded on select SKUs, and depending. on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email (“Initial Term”). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.
13. RAID configuration is optional and does require a second hard drive.
14. Firmware TPM is version 7.2.4.1. Hardware TPM is v2.0.
15. HP Support Assistant requires Windows and Internet access.

System Technical Specifications

SYSTEM BOARD

System Board Form Factor	H: 12.54" [318.39mm] W: 11.54" [293.36mm]
Processor Socket	Intel LGA-4710
CPU Bus Speed	DMI Gen4 x 8 lanes
Chipset	Intel W890 Arrow Lake- WS PCH
Super I/O Controller	Nuvoton SIO24
Memory Expansion Slots	8 DDR5 RDIMM memory slots
Memory Type Supported	DDR5, RDIMM (Registered) ECC
Memory Modes	Non-Interleaving for single channel. Interleaving when multiple channels are populated
Memory Speed Supported	6400MT/s for 1DPC and 5200MT/s for 2DPC; DDR5
Memory Protection	ECC on data
Maximum Memory	512GB
Memory Configuration (Supported)	16GB, 32GB and 64GB RDIMMs are supported. 16GB and 32GB RDIMMs can be mixed in a system.
PCI Express Connectors	• 3 PCI Express Gen5 slot x16 mechanical/ x16 electrical, CPU slot (full height, full length) • 1 PCI Express Gen5 slot x4 mechanical/ x4 electrical, CPU slot (full height, half length) • 1 PCI Express Gen4 slot x4 mechanical/ x4 electrical, PCH slot (full height, half length) • 4 M.2 Slots (PCIe Gen5 x4) • 1 Front NVMe Storage (MCIO PCIe Gen5 x8) • 1 Flex I/O (PCIe Gen3 x2) • 1 Network Header (SlimSAS PCIe Gen4 x4)
Supported Interfaces	

Integrated RAID

		RAID 0	RAID 1	RAID 5	RAID 10
Standard Factory Configuration	NVMe	On-Board Boot (Max 2)	On-Board Boot	-	-
	SATA	-	-	-	-
	Supported Operating Systems: Windows 11				
Factory Services	NVME	Boot & Data All Supported Locations	Boot & Data All Supported Locations	Boot & Data All Supported Locations	Boot & Data All Supported Locations
	SATA	Boot & Data All Supported Locations	Boot & Data All Supported Locations		

	Supported Operating Systems: Windows 11, RHEL 8.6 and later, SLE 15 SP4 and later, and Ubuntu 20.04 or later

Note: HP only supports VROC (Intel) RAID configurations for Standard Factory configurations. Factory Services may be able to provide other RAID configurations.
Note: Intel VROC RAID configurations available summer 2026.

SATA	Number of SATA ports: 2 Intel® SATA controller: primary SATA	
Integrated Graphics	No	
Network Controller	WGI219LM LOM provides Management capabilities: WOL, PXE 2.1, DASH 1.2 and AMT	
External SATA (eSATA)	No	
IDE connector	No	
Floppy connector	No	
Serial	1 internal header (requires optional Serial Port Adapter Kit)	
2nd Serial	No	
HD Integrated Audio	Yes	
USB Connector(s)	**Front**	Front I/O Entry: Four 5Gbps USB-A ports (Left-most Port has Charging Capability) Front I/O Premium: Two 5Gbps (Left-most Port has Charging Capability) Two 20Gbps Type-C™ (Ports have PD3.0 Capability) •Charging Ports provide 1.5 Amps @ 5 Volts • Standard USB Type A Ports provide 900mA @ 5 Volts • USB Type C Ports provide 3 Amps @ 5 Volts
	Rear	Five 5Gbps Type-A ports and one 10Gbps Type-C port. And Two5Gbps Type-A ports (Optional via Flex module) or Two 10Gbps Type-C port (Optional via Flex module).
	Internal	One 5Gbps USB header, with a single 12-pin shrouded connector. This header supports a USB Media Card reader. One USB2.0 single port header.
HD Integrated Audio	Yes	
Flash ROM	Yes	
CPU Fan Header	Yes	
Memory Fan Header	Yes (dual header)	
Chassis Fan Header	2 front, one rear	
Front PCI Fan Header	Yes	
Front Control Panel/Speaker Header	Yes	

System Technical Specifications

CMOS Battery Holder - – Lithium	Yes
Integrated Trusted Platform Module	Integrated TPM 2.0. The TPM module is disabled where restricted by law.
Power Supply Headers	Yes
Power Switch, Power LED & Hard Drive LED Header	Yes
Clear Password Jumper	Yes
Keyboard/Mouse	USB Only
Power Supply	1350W @110V or 1700W @200V or higher 775W

System Technical Specifications

SYSTEM COMFIGURATIONS

HP Z4 G6i Configuration #1	
Processor Info	Intel Xeon 634 4.60G 48 MB 12 cores 150W CPU
Memory Info	16GB (1x16GB) DDR5 6400 DIMM ECC REG Memory
Graphics Info	1x NVIDIA RTX A400 4 GB 4mDP Graphics
Disks/Optical/Floppy	1x 4TB Internal M.2 SSD + 1x DVDRW SATA
PSU	775W EPA92 Power Supply
Other	

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	69.17		69.2		68.8	
Windows short Idle (S0)	76.21		77.9		76.5	
Windows Busy Typ (S0)	192.05		193.1		193.6	
Windows Busy Max (S0)	212.9		213.4		212.4	
Sleep (S3)	6.74	6.64	6.78	6.74	6.64	6.78
Off (S5)	3.8	3.72	3.88	3.8	3.72	3.88
Zero Power Mode (EuP)	0.23		0.24		0.23	

Heat Dissipation (Btu/hr)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	260.04		265.81		261.03	
Windows short Idle (S0)	236.02		236.12		234.76	
Windows Busy Typ (S0)	655.30		658.88		660.59	
Windows Busy Max (S0)	726.44		728.15		724.74	
Sleep (S3)	23.00	22.66	23.13	23.00	22.66	23.13
Off (S5)	12.97	12.69	13.24	12.97	12.69	13.24
Zero Power Mode (EuP)	0.78		0.82		0.78	

System Technical Specifications

HP Z4 G6i Configuration #2	
Processor Info	Intel Xeon 654 4.80G 72 MB 18 cores 200W CPU
Memory Info	64GB (4x16GB) DDR5 6400 DIMM ECC REG Memory
Graphics Info	1x NVIDIA RTX PRO 2000 Blackwell 16 GB 4mDP Graphics
Disks/Optical/Floppy	1x 4TB Internal SATA HDD + 2x 4TB Internal M.2 SSD + 1x DVDRW SATA
PSU	775W EPA92 Power Supply
Other	

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	78.32		79.21		79.34	
Windows short Idle (S0)	89.14		87.2		87.6	
Windows Busy Typ (S0)	298.6		297.6		298.5	
Windows Busy Max (S0)	322.1		321.8		322.3	
Sleep (S3)	7.91	7.82	7.9	7.91	7.82	7.9
Off (S5)	3.73	3.64	3.78	3.73	3.64	3.78
Zero Power Mode (EuP)	0.227		0.236		0.228	

Heat Dissipation (Btu/hr)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	267.24		270.28		270.72	
Windows short Idle (S0)	304.16		297.54		298.90	
Windows Busy Typ (S0)	1018.87		1015.45		1018.52	
Windows Busy Max (S0)	1099.05		1098.03		1099.73	
Sleep (S3)	26.99	26.68	26.96	26.99	26.68	26.96
Off (S5)	12.73	12.42	12.90	12.73	12.42	12.90
Zero Power Mode (EuP)	0.77		0.81		0.78	

System Technical Specifications

HP Z4 G6i Configuration #3	
Processor Info	Intel Xeon 658X 4.90G 144 MB 24 cores 250W CPU
Memory Info	128GB (4x32GB) DDR5 6400 DIMM ECC REG Memory
Graphics Info	1x NVIDIA RTX PRO 4000 Blackwell 24 GB 4DP Graphics
Disks/Optical/Floppy	1x 8TB Internal SATA HDD + 2x 8TB Internal M.2 SSD + 1x DVDRW SATA
PSU	1200/1350W EPA92 Power Supply
Other	

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	149.14		148.63		149.25	
Windows short Idle (S0)	159.93		159.83		159.98	
Windows Busy Typ (S0)	452.4		453.8		452.6	
Windows Busy Max (S0)	490.2		492.6		490.8	
Sleep (S3)	8.01	7.9	8.02	8.01	7.9	8.02
Off (S5)	3.69	3.57	3.72	3.69	3.57	3.72
Zero Power Mode (EuP)	0.226		0.228		0.226	

Heat Dissipation (Btu/hr)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	508.89		507.15		509.26	
Windows short Idle (S0)	545.70		545.36		545.87	
Windows Busy Typ (S0)	1543.65		1548.43		1544.33	
Windows Busy Max (S0)	1672.63		1680.82		1674.68	
Sleep (S3)	27.33	26.96	27.37	27.33	26.96	27.37
Off (S5)	12.59	12.18	12.69	12.59	12.18	12.69
Zero Power Mode (EuP)	0.77		0.78		0.77	

System Technical Specifications

HP Z4 G6i Configuration #4	
Processor Info	Intel Xeon 676X 4.90G 144 MB 32 cores 275W CPU
Memory Info	256GB (4x64GB) DDR5 6400 DIMM ECC REG Memory
Graphics Info	1x NVIDIA RTX PRO 6000 Blackwell Max-Q 300W 96 GB 4DP Graphics
Disks/Optical/Floppy	1x 12TB Internal SATA HDD + 4x 8TB Internal M.2 SSD + 1x DVDRW SATA
PSU	1200/1350W EPA92 Power Supply
Other	

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	126.5		125.3		127.1	
Windows short Idle (S0)	140.5		141.2		142.1	
Windows Busy Typ (S0)	513.1		511.6		512.6	
Windows Busy Max (S0)	572.9		573.1		572.6	
Sleep (S3)	8.76	8.53	8.75	8.76	8.53	8.75
Off (S5)	3.52	3.46	3.54	3.52	3.46	3.54
Zero Power Mode (EuP)	0.25		0.26		0.25	

Heat Dissipation (Btu/hr)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	431.64		427.54		433.68	
Windows short Idle (S0)	479.41		481.79		484.87	
Windows Busy Typ (S0)	1750.77		1745.64		1749.06	
Windows Busy Max (S0)	1954.82		1955.50		1953.79	
Sleep (S3)	29.89	29.11	29.86	29.89	29.11	29.86
Off (S5)	12.01	11.81	12.08	12.01	11.81	12.08
Zero Power Mode (EuP)	0.85		0.89		0.85	

System Technical Specifications

HP Z4 G6i Configuration #5	
Processor Info	Intel Xeon 678X 4.90G 192 MB 48 cores 300W CPU
Memory Info	512GB (8x64GB) DDR5 6400 DIMM ECC REG Memory
Graphics Info	1x NVIDIA RTX PRO 6000 Blackwell 96 GB 4DP Graphics
Disks/Optical/Floppy	4x 8TB Internal M.2 SSD + 2x 8TB Front Accessible M.2
PSU	1200/1350W EPA92 Power Supply
Other	

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	148.81		147.76		147.6	
Windows short Idle (S0)	158.5		157.9		158.4	
Windows Busy Typ (S0)	973.5		978.4		973.6	
Windows Busy Max (S0)	1027.3		1026.5		1029.6	
Sleep (S3)	10.6	9.9	10.5	10.6	9.9	10.5
Off (S5)	3.81	3.61	3.84	3.81	3.61	3.84
Zero Power Mode (EuP)	0.25		0.26		0.25	

Heat Dissipation (Btu/hr)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	507.76		504.18		503.63	
Windows short Idle (S0)	540.82		538.78		540.48	
Windows Busy Typ (S0)	3321.72		3338.44		3322.06	
Windows Busy Max (S0)	3505.29		3502.56		3513.14	
Sleep (S3)	36.17	33.78	35.83	36.17	33.78	35.83
Off (S5)	13.00	12.32	13.10	13.00	12.32	13.10
Zero Power Mode (EuP)	0.85		0.89		0.85	

NOTE: The Power Supply Efficiency report may be found at the following links:
https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

System Technical Specifications

POWER SUPPLY

Operating Voltage Range	90-269VAC
Rated Voltage Range	100-240VAC
Rated Line Frequency	50-60 Hz
Frequency Range	47-66Hz
Heat Dissipation	Typical: 444 btu/hr (112 kcal/hr) Maximum: 1484 btu/hr (374 kcal/hr)
ENERGY STAR® certified (Config Dependent)	Yes
CECP Compliant @ 220V	YES
FEMP Standby Power Compliant	Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off
Built-in Self Test (BIST) **LED**	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes
Hood Lock Header	Yes
ErP Lot 6- Tier 1 Compliance @ 230V (<1W in S5 - –Power Off)	Yes
ErP Lot 6- Tier 2 Compliance @ 230V (<0.5W in S5 - Power Off)	Yes

Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)

System Configuration (Entry-level)	**Processor Info**	Intel Xeon 634 4.60G 48 MB 12 cores 150W CPU
	Memory Info	16GB (1x16GB) DDR5 6400 DIMM ECC REG Memory
	Graphics Info	1x NVIDIA RTX A400 4 GB 4mDP Graphics
	Disks/Optical	1x 4TB Internal M.2 SSD + 1x DVDRW SATA
	Power Supply	775W EPA92 Power Supply

Declared Noise Emissions		**Sound Power** (LWAd, bels)	**Deskside Sound Pressure** (LpAm, decibels)
	Idle	4.1	25
	Hard drive Operating (Drive Random Seek)		
	Hard drive Operating (Active mode)	4.1	25

System Technical Specifications

System Configuration (Mid-end)	**Processor Info**	Intel Xeon 658X 4.90G 144 MB 24 cores 250W CPU
	Memory Info	128GB (4x32GB) DDR5 6400 DIMM ECC REG Memory
	Graphics Info	1x NVIDIA RTX PRO 4000 Blackwell 24 GB 4DP Graphics
	Disks/Optical	1x 8TB Internal SATA HDD + 2x 8TB Internal M.2 SSD + 1x DVDRW SATA
	Power Supply	1200/1350W EPA92 Power Supply

Declared Noise Emissions		**Sound Power** (LWAd, bels)	**Deskside Sound Pressure** (LpAm, decibels)
	Idle	4.1	24
	Hard drive Operating (Drive Random Seek)	4.2	25
	Hard drive Operating (Active mode)	4.2	25

System Configuration (High-end)	**Processor Info**	Intel Xeon 678X 4.90G 192 MB 48 cores 300W CPU
	Memory Info	512GB (8x64GB) DDR5 6400 DIMM ECC REG Memory
	Graphics Info	1x NVIDIA RTX PRO 6000 Blackwell 96 GB 4DP Graphics
	Disks/Optical	4x 8TB Internal M.2 SSD + 2x 8TB Front Accessible M.2
	Power Supply	1200/1350W EPA92 Power Supply

Declared Noise Emissions		**Sound Power** (LWAd, bels)	**Deskside Sound Pressure** (LpAm, decibels)
	Idle	4.2	26
	Hard drive Operating (Drive Random Seek)		
	Hard drive Operating (Active mode)	4.2	27

Environmental Requirements	**Temperature**	Operating: 5° to 40°C (40° to 104°F)[1] Non-operating: -40° to 60°C (-40° to 140°F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation. Maximum rate of change: 10 °C/hr No direct sustained sunlight
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing

	Maximum Altitude	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation.
	Dynamic	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)* square: 422 cm/s, 20g *PCIe devices mass <1.3kg NOTE: Values represent individual shock events and do not indicate repetitive shock events Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz NOTE: Values do not indicate continuous vibration.
	Dynamic	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)* square: 422 cm/s, 20g *PCIe devices mass <1.3kg NOTE: Values represent individual shock events and do not indicate repetitive shock events Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz NOTE: Values do not indicate continuous vibration.

System Technical Specifications

PHYSICAL SECURITY AND SERVICEABILITY

Access Panel	Tool-less
Optical Drive	Tool-less, requires a 5.25" bay carrier
Hard Drives	Tool-less
Expansion Cards	Tool-less if card mass <1.3 kg
Processor Socket	Screw-in processor coolers
Blue User Touch Points	Yes, on tool-less internal chassis mechanisms
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Tool-less
Dual Color Power and HD LED on Front of Computer	Yes
Over-Temp Warning on Screen	Yes
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 10 seconds
Padlock Support	Padlock Loop (Rear): A rear bracket lets you attach a padlock (not included) to help secure the system and deter theft.
Cable Lock Support	Kensington Cable Lock (optional): Helps prevent theft of the entire system by securing it to a fixed object. The system includes a standard 3mm x 7mm Kensington lock slot located at the rear.
Universal Chassis Clamp Lock Support	No
Solenoid Lock and Hood Sensor	No
Rear Port Control Cover	No
Serial, USB, Audio, Network, Enable/Disable Port Control	New options. Not USB per port, filter out non hid pre boot environment
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration
3.3V Aux Power LED on System PCA	No
NIC LEDs (integrated) (Green & Amber)	Yes
CPUs and Heatsinks	A torx driver (T30) is needed to remove the processor heatsink. CPU attached to heatsink via tool-less clip
Power Supply Diagnostic LED	Yes
Front Power Button	Yes

System Technical Specifications

Front Power LED	Yes, white (normal), red (fault)
Front Hard Drive Activity LED	Yes, white
Front ODD Activity LED	Yes, on device
Internal Speaker	Yes
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solutions	Air cooled forced convection
Power Supply Fans	80 mm x 80 mm x 25 mm
CPU Heatsink Fan	108 mm x 108 mm x 25 mm
Chassis Fan	120 mm x 120 mm x 38 mm
Memory Heatsink Fan	Dual 60 mm x 60 mm x 25 mm
HP PC Hardware Diagnostics UEFI	HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support.
Access Panel Key Lock	Yes, top panel
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI). • Allows the system to wake from a low power mode. • Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
Integrated Chassis Handles	Yes, Rear full-grip handle and front ledge for easier handling.
Power Supply	Requires T15 Torx or flat blade screwdriver
PCI Card Retention	Yes, rear (all), middle (full-height cards), front (cards with extender).
Flash ROM	Yes
Diagnostic Power Switch LED on board	Yes
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes
DIMM Connectors	Yes

Service, Support, and Warranty

On-site Warranty and Service[1]: One-year, limited warranty and service offering delivers on-site, next business-day2 service for parts and labor and includes free telephone support[3] 8am - 5pm. Global coverage[2] ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP waranty. Hard drive storage devices are not covered under warranty for 24/7 operation except for Enterprise class hard drives.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.
NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries. HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

• USGv6 compliant for Windows OS (USGv6 Compliance Report)
• Completed ISO/IEC 17025 accredited testing designed specifically for the USGv6 Test Program. USGv6 is a test program designated by NIST that provides a proof of compliance to IPv6 (Internet Protocol version 6) specifications outlined in current industry standards for common network products. It is meant as a strategic planning guide for USG (United States Government) IT acquisitions to help ensure the completeness, correctness, interoperability and security of early IPv6 product offerings so as to protect early USG investments in the technology. (source: UNH)

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics
-

Please contact techregshelp@hp.com

System Technical Specifications

BIOS

BIOS 64-bit Services	BIOS supports 64-bit Operating systems.
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS Reference Specification, Version 3.5
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes: • NORMAL – normal temperature ranges. • ALERTED – excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. • SHUTDOWN – excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.5 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI Sleep State)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded

System Technical Specifications

	into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
UEFI Specification Revision	2.9
ACPI	Advanced Configuration and Power Management Interface, Version 6.5
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
PCI	PCI Firmware Specification, Revision 3.0
PCI Express	PCI Express Base Specification, Revision 5.0
SATA	Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	JEDEC JESD300-5
TPM	Trusted Computing Group TPM Specification Version 2.0. Common Criteria EAL4+ certified. FIPS 140-3 Certification TCG TPM Certified products list: http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
xHCI Specification	eXtensible Host Controller Interfacefor Universal Serial Bus Revision 1.2
USB	Universal Serial Bus Revision 1.1 Specification Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification
SMBIOS	System Management BIOS Reference Specification, Version 3.5

System Technical Specifications

SOCIAL AND ENVIRONMENTAL RESPOSIBILITY

Eco-Label Certifications & Declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold with Climate+ registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- Product Carbon Footprint
- At least 25% ocean bound plastic in system fans and 30% ocean bound plastic in the speaker[1]
- At least 60% post-consumer recycled plastic[2]
- At least 20% recycled metal[3]
- Low Halogen[4]
- 100% of HP paper-based packaging is from recycled or certified sustainable sources[5]
- Bulk packaging available

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the workstation model is based on a “Typically Configured workstation”.

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Sort idle)	76.520	77.420	79.140
Normal Operation (Long idle)	74.650	75.910	77.650
Sleep	6.880	6.911	6.820
Off	3.471	3.477	3.655

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

System Technical Specifications

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	260.933	264.002	269.867
Normal Operation (Long idle)	254.556	258.853	264.786
Sleep	23.460	23.566	23.256
Off	11.836	11.856	12.463

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	**Sound Power (L_{WAd}, bels)**	**Sound Pressure (L_{pAm}, decibels)**
Typically Configured – Idle	4.1	24
Fixed Disk – Random writes	4.2	25
Optical Drive – Sequential reads	4.2	25

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with EPEAT 2025 criteria at the Gold level, see http://www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 95.8% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	TBD
	PAPER/Molded Pulp	TBD
	PLASTIC/Polyethylene low density - –LDPE	TBD

The plastic packaging material contains at least 100% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. HP Inc. was one of the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide via the HP General Specification for the Environment (GSE). HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

HP Inc. believes the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. HP Inc. has supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

System Technical Specifications

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c05998906):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:
https://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c05403198
or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or

disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: HP Product Disassembly Instruction Website. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

- Sustainable Impact Report
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843
- Eco-label certifications
  - https://www.hp.com/us-en/sustainable-impact/document-reports.html#filters_documents_reports-=document_type-type_energy_star,type_epeat,type_tcoISO
- ISO 14001 certificates
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932

footnotes

1. Percentage of ocean-bound plastic contained in each component varies by product. Ocean Bound plastic is expressed as a percentage of the total weight plastic. Ocean Bound plastic is based on the definition set by the UL2809 standard.
2. Post-consumer recycled plastic is expressed as a percentage of the total weight of the plastic, based on the definition set in the EPEAT criteria.
3. Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.
4. External power supplies, WWAN modules, power cords, cables and peripherals excluded. Service parts obtained after purchase may not be Low Halogen.
5. HP paper and fiber-based packaging for PCs, displays, home and office print, and supplies is reported by suppliers as recycled or certified, with a minimum of 97% by volume verified by HP. Packaging is the box that comes with the product and all paper-based materials inside the box. Packaging for personal systems accessories and spare parts is not included. Plastic cushions are made from >90% recycled plastic.

System Technical Specifications

MANAGEABILITY

Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality: • DASH 1.2 (via Intel® LAN on motherboard)
Intel® Active Management Technology (AMT)	Intel® Active Management Technology (AMT) 19.10 An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 19.10 includes the following advanced management functions: • Power Management (on, off, reset, graceful shutdown, sleep and hibernate) o Support in Max Power Savings (Shutdown and Hibernate Modes) • Hardware Inventory (includes BIOS and firmware revisions) • Hardware Alerting • Agent Presence • System Defense Filters • Serial Over LAN (SOL) • USB Redirect (Media Redirection) • ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled • DASH 1.2 compliance • IPv6 Support • Fast Call for Help - a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection • Remote Scheduled Maintenance - pre-schedule when the system connects to the IT or service provider console for maintenance. • Remote Alerts - automatically alert IT or service provider if issues arise • Access Monitor - Provides oversight into Intel® AMT actions to support security requirements • PC Alarm Clock • Microsoft NAP Support • Host Base set-up and configuration • Management Engine (ME) firmware roll back with same SVN number • Local Time Sync to UTC • Remote Memory Dump Command – Creates memory dump for debug
Intel® vPro® Technology	Yes, when configured with an Intel® vPro™ supporting processor.

1.HP Care Pack Services are extended service contracts that go beyond the standard limited warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications - Storage and Drives

STORAGE

HP Z Turbo 512GB PCIe-4x4 2280 TLC M.2 SSD	**Capacity**	512GB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	300 TBW
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrica
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	6400MB/s[1]
	Sequential Write	3400MB/s[1]
	Random Read	600K IOPS[1]
	Random Write	600K IOPS[1]
HP Z Turbo 512GB PCIe-4x4 2280 SED OPAL2 TLC M.2 SSD	**Capacity**	512GB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	300 TBW
	Reliability	1.5M hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	6400MB/s
	Sequential Write	3400MB/s
	Random Read	600K IOPS
	Random Write	600K IOPS
	Self-Encrypting Drive Support	OPAL2
512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	512 GB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	320 TBW
	Reliability	1.5M hours
	Interface	PCI Express 3.0 x4 electrica
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 2500MB/s

Technical Specifications - Storage and Drives

	Random Read	up to 420K IOPS
	Random Write	up to 635K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
Citadel 512GB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	512 GB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	320TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 3.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 2500MB/s
	Random Read	up to 420K IOPS
	Random Write	up to 635K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
HP Z Turbo 1TB PCIe-4x4 2280 TLC M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	400TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS

1. Actual performance may vary.

Technical Specifications - Storage and Drives

HP Z Turbo 1TB PCIe-4x4 2280 SED OPAL2 TLC M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	400TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
	Self-Encrypting Drive Support	OPAL 2
Citadel 1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	1620 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 3.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 3000MB/s
	Random Read	up to 720K IOPS
	Random Write	up to 690K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
HP Z Turbo 1TB PCIe-5x4 2280 M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	400 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 10000MB/s
	Random Read	up to 1500K IOPS

	Random Write	up to 1300K IOPS
HP Z Turbo 1TB PCIe-5x4 2280 SED OPAL2 M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	400 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 10000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
	Self-Encrypting Drive Support	OPAL2
HP Z Turbo 2TB PCIe-4x4 2280 TLC M.2 SSD	**Capacity**	2 TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
HP Z Turbo 2TB PCIe-4x4 2280 SED OPAL2 TLC M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s

Technical Specifications - Storage and Drives

	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
	Self-Encrypting Drive Support	OPAL2
HP Z Turbo 2TB PCIe-5x4 2280 M.2 NMIC SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
HP Z Turbo 2TB PCIe-5x4 2280 SED OPAL2 M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
	Self-Encrypting Drive Support	OPAL2
HP Z Turbo 4TB PCIe-4x4 2280 M.2 SSD	**Capacity**	4TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	600 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	

	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
HP Z Turbo 4TB PCIe-4x4 2280 SED OPAL2 M.2 SSD	**Capacity**	4TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	600 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
	Self-Encrypting Drive Support	OPAL2
HP Z Turbo 4TB PCIe-5x4 2280 M.2 SSD	**Capacity**	4TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	600 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
HP Z Turbo 8TB PCIe-4x4 2280 NVMe M.2 SSD	**Capacity**	8TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	2400 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)

Technical Specifications - Storage and Drives

	Performance	
	Sequential Read	up to 6500MB/s
	Sequential Write	up to 5000MB/s
	Random Read	up to 800K IOPS
	Random Write	up to 800K IOPS
1TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	1TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	1620 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 3.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 3000MB/s
	Random Read	up to 720K IOPS
	Random Write	up to 690K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
HP Z Turbo 2TB PCIe-5x4 2280 M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
Citadel 2TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	3140 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 3.0 x4 electrical

Technical Specifications - Storage and Drives

	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 3000MB/s
	Random Read	up to 720K IOPS
	Random Write	up to 690K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
2TB PCIe-3x4 2280 NVMe SED OPAL2 FIPS 140-2 TLC M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	3140 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 3.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 3400MB/s
	Sequential Write	up to 3000MB/s
	Random Read	up to 720K IOPS
	Random Write	up to 690K IOPS
	Self-Encrypting Drive Support	OPAL2/FIPS 140-2
4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	**Capacity**	4TB
	Protocol	SATA
	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M Hours
	Rated Power On Hours	8760/yr
	Annualized Failure Rate (based on Rated POH)	<0.62%
	Width	
	Media Diameter	3.5in; 8.9 cm
	Physical Size	4 in; 10.17cm
	Interface	Serial ATA (6.0Gb/s), NCQ enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s
	Buffer	256MB
	Seek Time (typical reads, includes controller overhead, including settling)	
	Single Track	0.7ms [1]
	Average	8.5ms [1]
	Full Stroke	15.7ms [1]

Technical Specifications - Storage and Drives

	Rotational Speed	7,200 rpm
	Operating Temperature	41° to 131° F (5° to 55° C)
	Performance	
	Sequential Read	up to 226MB/s
	Sequential Write	up to 226MB/s
	Enterprise Class Features	High Reliability
8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	**Capacity**	8TB
	Protocol	SATA
	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M Hours
	Rated Power On Hours	8760/yr
	Annualized Failure Rate (based on Rated POH)	<0.62%
	Width	
	Media Diameter	3.5in; 8.9 cm
	Physical Size	4 in; 10.17cm
	Interface	Serial ATA (6.0Gb/s), NCQ enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s[1]
	Buffer	256MB
	Seek Time (typical reads, includes controller overhead, including settling)	
	Single Track	0.7ms
	Average	8.5ms
	Full Stroke	15.7ms
	Rotational Speed	7,200 rpm
	Operating Temperature	41° to 131° F (5° to 55° C)
	Performance	
	Sequential Read	up to 226MB/s
	Sequential Write	up to 226MB/s
	Enterprise Class Features	High Reliability
12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	**Capacity**	12TB
	Protocol	SATA
	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M Hours
	Rated Power On Hours	8760/yr
	Annualized Failure Rate (based on Rated POH)	<0.62%
	Width	
	Media Diameter	3.5in; 8.9 cm

Technical Specifications - Storage and Drives

Physical Size	4 in; 10.17cm
Interface	Serial ATA (6.0Gb/s), NCQ enabled
Synchronous Transfer Rate (Maximum)	Up to 600MB/s[1]
Buffer	128MB
Seek Time (typical reads, includes controller overhead, including settling)	
Single Track	0.7ms
Average	8.5ms
Full Stroke	15.7ms
Rotational Speed	7,200 rpm
Operating Temperature	41° to 131° F (5° to 55° C)
Performance	
Sequential Read	up to 226MB/s
Sequential Write	up to 226MB/s
Enterprise Class Features	High Reliability

Technical Specifications - Graphics

GRAPHICS

NVIDIDA RTX A400 4 GB Graphics	**Form Factor**	Half Height, Single Slot (2.7" Height x 6.4" Length)
	Graphics Controller	Max Power: 50 Watts Cooling Solution: Active fan heatsink
	Bus Type	
	Memory	4GB GDDR6 Memory Bandwidth: 96 GB/s Memory Width: 128-bit
	Connectors	4x Mini DisplayPort 1.4a
	Maximum Resolution	4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	Image Quality Features	Advanced support for 8-bit and 10-bit per RGB color component. High bandwidth scaler for high quality up and downscaling
	Display Output	4 full physical DP1.3 HBR3 / DP1.4 HDR outputs FreeSync support
	GPU Architecture	GCN 4th Generation
	Shading Architecture	Shader Model 5.1
	Supported Graphics APIs	DirectX®12 OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0
	Available Graphics Drivers	Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions) HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX™ A1000 8GB	**Form Factor**	Single Slot, Low Profile (2.7” H x 6.1” L)
	Graphics Controller	Max Power: 50 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 4.0 x 8
	Memory	4GB GDDR6 Memory Bandwidth: 96 GB/s Memory Width: 128-bit
	Connectors	4x Mini DisplayPort 1.4a
	Maximum Resolution	4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Technical Specifications - Graphics

	Image Quality Features	Advanced support for 8-bit and 10-bit per RGB color component. High bandwidth scaler for high quality up and downscaling
	Display Output	4 full physical DP1.3 HBR3 / DP1.4 HDR outputs FreeSync support
	GPU Architecture	GCN 4th Generation
	Shading Architecture	Shader Model 5.1
	Supported Graphics APIs	DirectX®12 OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0
	Available Graphics Drivers	Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions) HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA RTX PRO 2000 Blackwell 16 GB Graphics	**Form Factor**	Half Height, Half Length (HHHL) 6.6", Double-slot NVIDIA Form Factor 6.0 Compliant
	Graphics Controller	Max Power: 70 Watts Thermal Solution: Active Cooled
	Bus Type	PCI Express 5.0 x 8 Lane and polarity reversal supported
	Memory	16GB GDDR7 with ECC Memory Bandwidth: Up to 288 GB/s Memory Bus width: 128 bits
	Connectors	4x mini DisplayPort 2.1b
	Maximum Resolution	3840 × 2160 × 24 bpp at 480Hz1 7680 × 4320 × 24 bpp at 165Hz1
	GPU Architecture	Blackwell
	Shading Architecture	Shader Model 6.7
	Supported Graphics APIs	DirectX 12 Shader Model 6.7 OpenGL 4.65 Vulkan 1.4
	Available Graphics Drivers	Linux: 570. 190 or later Windows: 570 or later

Technical Specifications - Graphics

NVIDIA RTX PRO 4000 Blackwell 16 GB Graphics	**Form Factor**	Full-height, full-length (FHFL) 9.5”, single-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 145W Thermal Solution: Active cooled
	Bus Type	PCI Express 5.0 ×16
	Memory	24GB Memory Bandwidth: Up to 672 GB/s Memory Width: 192 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 3840 x 2160 @ 165 Hz 2x 7680 x 43320 @ 100 Hz
	GPU Architecture	Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.6 Vulkan 1.3
	Available Graphics Drivers	Linux: 570. 169 or later Windows: 570 or later
NVIDIA RTX PRO 4500 Blackwell 32 GB Graphics	**Form Factor**	Full-height, full-length (FHFL) 10.5”, dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 200W Thermal SOlution: Active cooled
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	32GB GDDR7 with ECC Memory Bandwidth: Up to 896 GB/s Memory Width: 256 bits
	Connectors	4 x DisplayPort 2.1b
	Maximum Resolution	4x 3840 x 2160 @ 165 Hz 2x 7680 x 4320 @ 100 Hz
	GPU Architecture	NVIDIA Blackwell
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570. 169 or later Windows: 570 or later

Technical Specifications - Graphics

NVIDIA RTX PRO 5000 Blackwell 32 GB Graphics	**Form Factor**	Full-height, full-length (FHFL) 10.5”, dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 300W Thermal Solution: Active cooling
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	48 GB GDDR7 with ECC Memory Bandwidth: Up to 1344 GB/s Memory Width: 384 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 4,096 x 2,160 @ 120 Hz 4x 5,120 x 2,880 @ 60 Hz 2x 7,680 x 4,320 @ 60 Hz
	GPU Architecture	NIVIDA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later
NVIDIA RTX PRO 6000 Blackwell Max-Q 300W 96 GB Graphics	**Form Factor**	Full-height, full-length (FHFL) 10.5”, dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 300W Thermal Solution: Active cooled
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	96 GB GDDR7 with ECC Memory Bandwidth: Up to 1792 GB/s Memory Width: 512 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 3840 x 2160 @ 165 Hz 2x 7680 x 4320 @ 100 Hz
	GPU Architecture	NVIDIA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3

Technical Specifications - Graphics

	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later
NVIDIA RTX PRO 6000 Blackwell 96 GB Graphics	**Form Factor**	Extra-height, full-length (XHFL) 12.3”, dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 600W Thermal Solution: Active Cooled
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	96 GB GDDR7 with ECC Memory Bandwidth: Up to 1792 GB/s Memory Width: 512 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	GPU Architecture	NVIDIA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later
NVIDIA A800 40 GB Graphics	**Form Factor**	Full-height, full-length (FHFL) 10.5”, dual-slot NVIDIA Form Factor 5.5 compliant
	Graphics Controller	Max Power: 240W Thermal Solution: Active Cooled
	Bus Type	PCI Express 4.0 ×16 Lane and polarity reversal supported
	Memory	40GB HBM2 Memory Bandwidth: Up to 1555 GB/s Memory Width: 5120 bits
	Connectors	N/A
	GPU Architecture	NVIDIA Ampere
	Available Graphics Drivers	Linux: R535 or later Windows: R535 or later

Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD Writer	**Description**	9.5mm height, tray-load	
	Mounting Orientation	Either horizontal or vertical	
	Interface Type	SATA/ATAPI	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Supported Media Types	DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW	
	Disc Capacity	**DVD-ROM**	8.5 GB DL or 4.7 GB standard
	Access Times	**Full Stroke DVD**	< 200 ms (seek)
		Full Stroke CD	< 200 ms (seek)
	Maximum Data Transfer Rates	**CD ROM Read**	CD-ROM, CD-R Up to 24X CD-RW Up to 24X
		DVD ROM Read	DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X
	Access Times	**Full Stroke DVD**	< 230 ms (typical)
		Full Stroke CD	< 220 ms (typical)
	Power	**Source**	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC -< 800 mA typical, <1600 mA maximum
	Operating Environmental (all conditions non-condensing)	**Temperature**	41° to 122° F (5° to 50° C)
		Relative Humidity	10% to 80%
		Maximum Wet Bulb Temperature	84° F (29° C)
	Operating Systems Supported	Windows 11 Linux®	
	Kit Contents	HP SATA DVD Writer drive, installation guide.	
	Weight	0.35 lbs. (0.16 kg)	

Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Drive	**Description**	9.5mm height, tray-load	
	Mounting Orientation	Either horizontal or vertical	
	Interface Type	SATA / ATAPI	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Supported Media Types	DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW	
	Disc Capacity	**DVD-ROM**	8.5 GB DL or 4.7 GB standard
	Access Times	**DVD-ROM Single Layer**	< 110 ms (typical)
		CD-ROM Mode 1	< 110 ms (typical)
		Full Stroke DVD	< 230 ms (typical)
		Full Stroke CD	< 220 ms (typical)
	Power	**Source**	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC – <800mA typical, < 1600 mA maximum
	Operating Environmental (all conditions non-condensing)	**Temperature**	41° to 122° F (5° to 50° C)
		Relative Humidity	10% to 80%
		Maximum Wet Bulb Temperature	84° F (29° C)
	Operating Systems Supported	Windows 11 Linux®	
	Kit Contents	HP SATA DVD Writer drive, installation guide.	

Technical Specifications - Networking and Communications

NETWORKING / COMMUNICATION

Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro™ with Intel® AMT 19.0)

Connector	RJ-45
Cabling	Twisted pair up to 100m
Controller	Intel® I219LM GbE platform LAN connect networking controller
Memory	3 KB Tx and 3KB Rx FIFO packet buffer memory
Data Rates Supported	10/100/1000 Mbps
Compliance	802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z
Bus Architecture	PCI Express and SMBus
Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)
Power Requirement	Requires 3.3V (integrated regulators for core Vdc)
Boot ROM Support	Yes
Network Transfer Mode	Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)
Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps
Management Capabilities	vPro, WOL, auto MDI crossover, PXE, Muti-port teaming, ACPI, Advanced cable diagnostic, loopback modes, AMT 19 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)

The onboard LAN supports RDP Wake on LAN function. If some networking device does not support Modern standby feature for WOL, HP suggests using this function as an alternate solution for WOL G3-S5/ S5/S4/MSC wake.
NOTE1: NDIS driver limitation when using Win11 OS, I219 switches to NDIS Driver and it only supports IPV4 wake from MSC. If using IPV6, I219 cannot wake up from MSC.
NOTE2: Cannot wake from S4 when using the NDIS Driver.

HP 1-Port 1GbE Flex IO NIC

Connector	RJ-45 (Single Port)
Cabling	1GbE over Category 5e (or better) up to 100m
Controller	Realtek 8153 Ethernet Controller
Data Rates Supported	10/100/1000 Mbps
Compliance	802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.1P Layer 2 Priority Encoding 802.3az (Energy Efficient Ethernet)
Bus Architecture	USB
Power Requirement	Requires 3.3V (integrated regulators for core Vdc)
Boot ROM Support	Yes
Network Transfer Mode	Full-duplex; Half-duplex

Technical Specifications - Networking and Communications

Network Transfer Rate	1000BASE-T Full-Duplex 100BASE-TX Full-Duplex 100BASE-TX Half-Duplex 10BASE-T Full-Duplex 10BASE-T Half-Duplex
Operating Temperature	32° to 131° F (0° to 55° C)
Dimensions (HxW)	1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)
Operating System Driver Support	Windows 11, Linux®

Intel® I226-T1 2.5GbE Ethernet Network Adaptor

Connector	RJ-45
Cabling	Cat 6 or better up to 100 meters
Controller	Intel® Ethernet I226 Controller
Network Transfer Rates Supported	2.5Gbps, 1Gbps, 100/10Mbps
Compliance	IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802.1AS-Rev, 802.1Qav, 802.1Qbu, 802.1Qbv, 802.3br, 802.3az
Data Path Width	PCIe Gen2x1
Network Transfer Rate	2.5Gbps, 1Gbps, 100/10Mbps
Data Path Width	PCIe Gen2x1
Power Requirement	1.2 Watts (typical)
Operating Temperature	32° to 158° F (0°C to 70°C)
Dimensions (HxW)	2.7 in x 2.57 in. (68.7mm x 65.3mm) [Excluding bracket]
Operating System Driver	Windows 11 64-Bit Linux®
Kit Contents	• Intel® I226-T1 1-Port 2.5GbE NIC with standard height bracket attached Low-profile bracket • Product Literature

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Connector	Dual-port SFP28
Cabling	Transceiver with Multi-Mode Fiber OM3 or OM4 (OM4 or better recommended)
Controller	ConnectX-6 Dx
Network Transfer Rates Supported	1/10/25 GbE
Data Path Width	PCIe Gen4x8
Power Requirement	19.74W Maximum power available through SFP28 port: 2.5W (each port)
Operating Temperature	32° to 131° F (0° to 55° C)
Dimensions (HxW)	6.22in. x 2.67in (158mm x 68mm)
Operating System Driver	Windows 11 64-Bit Linux®

Technical Specifications - Networking and Communications

Kit Contents	•NVIDIA Mellanox ConnectX-6 SFP28 25GbE NIC with standard height bracket attached • Low-profile bracket • Product Literature

The NVIDIA Mellanox ConnectX-6 DX network adapter requires either a PCIeG4 x4 or PCIeG4 x8 slot (electrical connection) to have full performance with two 25GbE SFP28 transceivers installed in the network adapter. When the network adapter is installed in a PCIeG3 x4 slot, the performance will be limited when installing two 25GbE SFP28 transceivers or installing a 25GbE SFP28 transceiver plus a 10GbE SFP+ transceiver.
Transceivers sold separately. Please select the appropriate transceiver speed for intended application.

HP 25GbE SFP28 LC Fiber Optic Transceiver

Connector	LC Fiber Optic Connector
Cabling	Typically, OM4 or higher MMF LC fiber optic cabling, up to 100m on OM4, up to 70m on OM3
Data Rates Supported	25Gbps
Compliance	SFF-8472 and 8431, Hot pluggable SFP+ footprint
Compatibility	Intended for use with NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE NIC
Wavelength	850nm
Kit Contents	25GbE SFP28 Transceiver

This transceiver only officially supports 25Gbps speed. It is not a multi-speed capable transceiver.

HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver

Connector	LC Fiber Optic Connector
Cabling	Typically, OM4 or higher MMF LC fiber optic cabling, up to 300m on MMF
Data Rates Supported	10Gbps
Compliance	SFF-8472 and 8431, Hot pluggable SFP+ footprint
Compatibility	Intended for use with NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE NIC
Wavelength	850nm
Kit Contents	10GbE SFP+ Transceiver

This transceiver only officially supports 10Gbps speed. It is not a multi-speed capable transceiver.

Intel® X550-T2 2-Port 10GbE NIC

Connector	Dual-port RJ-45
Cabling	Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m
Controller	Intel® Ethernet Controller X550-AT2
Network Transfer Rates Supported	10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE
Data Path Width	PCIe Gen3x4
Power Requirement	3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps
Operating Temperature	32° to 131° F (0° to 55° C)
Dimensions (HxW)	167 mm x 69 mm

Technical Specifications - Networking and Communications

Operating System Driver	Windows 11 64-Bit Linux®
Management Capabilities	DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP, Multi-mode I/O Virtualization, VxLAN, VMDq, VLAN support with VLAN tag insertion
Kit Contents	• Intel® X550-T2 2-Port 10GbE NIC with standard height bracket attached • Low-profile bracket • Product Literature

The Intel® X550-T2 NIC cannot support MSC (modern standby) / S4 / S5 wake. HP suggests customers can use Onboard Lan RDP wake to replace MSC Wake.

Allied Telesis AT2911Ta/2-901 Dual Port 1GbE NIC

Connector	2 x RJ-45 (Dual Port)
Cabling	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps up to 100m
Memory	17 Rx and 16 Tx queues
Network Transfer Rates Supported	10/100/1000 Mbps
Compliance	IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab (10/100/1000T) RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI
Bus Architecture	PCIe 2x1
Data Transfer Mode	PCIe-based interface
Power Requirement	2.4 Watts (typical)
Management Capabilities	VLAN support, Link aggregation LACP, Link aggregation smart switch, Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows Management Instrumentation (WMI), PXE 2.1, SNMP
Kit Contents	Allied Telesis AT-2911Ta/2-901 Dual Port 1GbE NIC with low-profile bracket attached and standard bracket included

The AT2911T/2-9 NIC cannot support MSC (modern standby) wake. HP suggests customers use Onboard Lan RDP wake to replace MSC Wake.

HP Flex 1GbE Fiber LC Single Port

Connector	LC Fiber (Single Port)
Cabling	LC Fiber Cabling
Controller	AT-29M2
Network Transfer Rates Supported	1GBASE-SX
Power Requirement	Up to 3.3 Watts
Bus Architecture	USB 3.1G1

Technical Specifications - Networking and Communications

Network Transfer Mode	1GBASE-SX
Network Transfer Rate	1GBASE-SX
Management Capabilities	PXE, Wake on LAN, Digital Diagnostic Monitoring
Kit Contents	HP 1GbE Fiber LC Single Flex Port NIC
HP 2.5GbE Flex Port	
Connector	RJ-45
Cabling	Cat6 or better up to 100 meters
Controller	Intel® I226-V
Memory	4 Tx and 4 Rx Queues, Jumbo Frames up to 9KB and without TSN
Network Transfer Rates Supported	10/100/1000Mbps and 2.5Gbps BASE-T
Compliance	IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802.1AS-Rev, 802.1Qav, 802.1Qbu, 802.1Qbv, 802.3br, 802.3az
Power Requirement	1.5 Watts (Typical)
Bus Architecture	PCIe Gen2x1
Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)
Network Transfer Mode	Automatic link configuration for speed duplex and flow control
Network Transfer Rate	2500BASE-T 1000BASE-T 100BASE-TX (Half-duplex supported) 10BASE-Te (Half-duplex supported)
Management Capabilities	WOL, PXE, UEFI, Error Correcting Memory in packet buffers, UDP/TCP/IP Checksum Offload, SCTP receive and transmit integrity offload
Kit Contents	HP 2.5GbE LAN Flex Port Networking Interface Card
10GBase-T Flex IO v2	
Connector	RJ-45
Cabling	Cat 6 or better for 10G, up to 100 meters
Controller	Realtek RTL8127
Network Transfer Rates Supported	10/100/1000Mbps and 2.5G/5G/10Gbps
Compliance	IEEE 1588 V1 and V2, IEEE 802.1AS, 802.3, 802.3az-2010, 802.3ab, 802.3u, 802.3bz, 802.1P, 802.1Q, 802.1ad
Power Requirement	3W
Bus Architecture	PCIe
Network Transfer Mode	10/100/1000M and 2.5G/5G/10G
Network Transfer Rate	10/100/1000M and 2.5G/5G/10G
Management Capabilities	WOL, PXE, UEFI
Kit Contents	10GBase-T Flex IO Module

Technical Specifications - Networking and Communications

Broadcom 5720 Dual Port 1GbE RJ45 PCIe Ethernet Network Adaptor

Connector	RJ-45
Cabling	Cat 5 or better, up to 100 meters
Controller	BCM5720
Network Transfer Rates Supported	10/100/1000Mbps
Compliance	IEEE 802.3ab, 802.3az-2010, 802.3x, 802.1q,
Power Requirement	2.3 Watts (maximum)
Bus Architecture	PCIe Gen2x1
Network Transfer Rate	10/100/1000Mbps
Management Capabilities	PXE, WOL
Kit Contents	BCM5720-2P adapter with full height bracket installed and half height bracket included

HP Dual Port 10GBase-T NIC Module G2

Connector	2 x RJ-45 (Dual Port)
Cabling	Cat 6a or better for 10G, up to 100 meters
Controller	2 x Marvell AQC113
Memory	128KB Tx Buffer, 192KB Rx Buffer on-chip
Network Transfer Rates Supported	10/100/1000 Mbps and 2.5/5/10 Gbps
Compliance	IEEE 802.3 - 2018, 802.1AS-2011
Power Requirement	7 Watts
Bus Architecture	PCI Express and SMBus
Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic
Network Transfer Mode	Full-duplex
Network Transfer Rate	10GBASE-T 5GBASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-TE
Management Capabilities	WOL, PXE, UEFI,
Kit Contents	HP 10GBase-T G2 Dual Port NIC Network Header Connector Cable Installation Instructions

Technical Specifications - Networking and Communications

AT-2914SX/LC PCIe Fiber Adaptor	
Connector	LC Fiber (Single Port)
Cabling	50/125 µm (core/cladding) multimode fiber optic cable up to 500m 62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m
Controller	BCM57762
Network Transfer Rates Supported	1000SX (1GbE Fiber at 850nm Wavelength)
Compliance	IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation) RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI
Power Requirement	1.5 Watts (typical)
Bus Architecture	PCIe x1
Data Transfer Mode	PCIe
Network Transfer Mode	1000SX only (1GbE Fiber at 850nm Wavelength)
Network Transfer Rate	1000SX only (1GbE Fiber at 850nm Wavelength)
Management Capabilities	UEFI, Smart Load Balancing and failover, Link aggregation (IEEE802.3ad), Generic trunking (FEC/GEC) / IEEE 802.3ad-draft static, VLAN Support, PXE
Kit Contents	Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-profile bracket attached and standard height bracket included

HP 10/25GbE SFP28 Fiber Network Module	
Connector	SFP28 Cages
Cabling	Dependent on transceiver, LC Fiber OM4 or better is recommended
Controller	Intel E810-XXVAM2
Network Transfer Rates Supported	25Gbps/10Gbps/1Gbps per port
Compliance	IEEE 1588, SFP28
Power Requirement	13 Watts
Bus Architecture	PCIe Gen 4
Data Transfer Mode	DACS: 25GBASE-CR (802.3by 25Gb Twinax), SFP+ Twinax, 10GBASE-SR, Optics and AOCs: 25GBASE-SR, 25GBASE-LR, 10GBASE-LR
Network Transfer Rate	25Gbps/10Gbps/1Gbps per port
Kit Contents	HP 10/25GbE SFP28 Fiber Network Module

Transceivers sold separately. Please select the appropriate transceiver speed for intended application.

Technical Specifications - Networking and Communications

Intel E810-CQDA2 1x100GbE/2x50GbE QSFP28 PCIe Network Adapter

Connector	QSFP28
Cabling	Dependent on installed transceiver
Controller	Intel E810-CAM
Network Transfer Rates Supported	100/50/25/10GbE per port (Maximum of 100Gbps total across both ports)
Compliance	IEEE 1588
Power Requirement	21 Watts Typical (27 Watt Max)
Bus Architecture	PCIe Gen4x16
Data Transfer Mode	DACs: IEEE 100GBASE-CR2/CR4, 50GBASE-CR/CR2, 25G/50G Consortium, 25GBASE-CR (CA-N, CA-S, CA-L), SFP+ 10GbE DAC Optics and AOCs: CAUI-4, 100GAUI-2/4, IEEE 50GAUI-1/2, IEEE LAUI-2, 25GBASE-SR/LR, 10GBASE-SR/LR
Network Transfer Rate	100/50/25/10GbE per port (Maximum of 100Gbps total across both ports)
Kit Contents	Intel E810-CQDA2 PCIe Network Adapter

Transceivers not included. Please select the appropriate transceiver speed for intended application.

HP MT7925 Wi-Fi 7 +Bluetooth® 5.4 WLAN with External Antenna

WLAN Standards	802.11a/b/g/n/ac/ax/be compliant
Antenna	External dipole antenna with 3 foot cable
Bluetooth Standards	5.4
Operating Temperature	Same as system
Interface	M.2 Controller communicates with host via PCIe slot and internal USB cable
Dimensions	PCIe Carrier with Controller - 3.5" x 2.25" (8.9cm x 5.7cm) Antenna - 2.5" x 2.5" base (6.4cm x 6.4cm), 5" tall (12.7cm)
Kit Contents	MT7925 M.2 Wi-Fi Controller installed in PCIe carrier card, external antenna, and internal USB cable

HP Flex IO MT7925 Wi-Fi 7 +Bluetooth® 5.4 WLAN with Integrated Antenna

WLAN Standards	802.11a/b/g/n/ac/ax/be compliant
Antenna	Dipole antenna integrated into system chassis
Bluetooth Standards	5.4
Operating Temperature	Same as system
Interface	M.2 Controller communicates with host via PCIe and USB in the Flex IO connector
Dimensions	1.5" x 1.5" (3.8cm x 3.8cm)
Kit Contents	MT7925 M.2 Wi-Fi Controller installed in Flex IO carrier card, integrated antenna installed in chassis

Available CTO only.

WEIGHTS & DIMENSIONS-Packaging

Packaging (WxDxH)	**EPE:** 12.32 x 23.35 x 24.02 in (313 x 593 x 610 mm) **MPP:** 12.32 x 23.35 x 24.02 in (313 x 593 x 610 mm)
Shipping Weight	**EPE:** 42.58 lb (19.33 kg) **MPP:** 44.69 lb (20.29 kg)
Palletization Profile	6 units per layer 3 layers max 18 units per pallet 1200 x 1000 x 1960 mm (pallet included)

Change Log

SUMMARY OF CHANGES

Date of change	Version History		Description of change
May 4, 2026	From v1 to v2	Update	General update

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